



MJ P-Channel Enhancement Mode Power MOSFET

Description

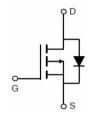
The MJ20P70G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

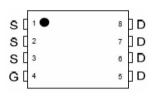
General Features

- $ightharpoonup V_{DS}=-20V, I_{D}=-70A$ $R_{DS(ON)}<3m\Omega$ @ V_{GS}=-4.5V $R_{DS(ON)}<4m\Omega$ @ V_{GS}=-2.5V $R_{DS(ON)}<8m\Omega$ @ V_{GS}=-1.8V
- ♦ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high Eas
- ◆ Excellent package for good heat dissipation

Application

- ◆ Load switch
- Battery protection







Schematic diagram

Pin Assignment

DFN5x6 -8L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ20P70G	MJ20P70G	DFN 5X6 -8L	-	-	-

Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-20	V
Gate-Source Voltage	Vgs	±10	V
Drain Current-Continuous	lo	-70	А
Drain Current-Continuous(Tc =100°C)	ID(100°C)	-49.5	А
Pulsed Drain Current (Note 1)	IDM	-280	А
Maximum Power Dissipation	Po	130	W
Derating factor		1.04	W/°C
Operating Junction and Storage Temperature Range	Тл ,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	0.96	°C/W	
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Electrical Characteristics (Tc =25°Cunless otherwise noted)

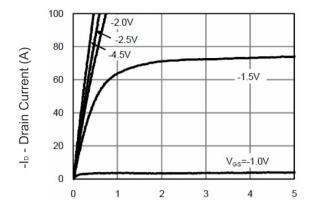
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'					
Drain-Source Breakdown Voltage	BVpss	V _{GS} =0V I _D =-250μA	-20	-	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =-20V,V _{GS} =0V	_	-	1	μΑ
Gate-Body Leakage Current	lgss	V _{DS} =±10V,V _{DS} =0V	_	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =-250µA	-0.4	-0.6	-1.0	V
		V _{GS} =-4.5V, I _D =-20A	-	2.3	3	mΩ
Drain-Source On-State Resistance	Rds(on)	V _{GS} =-2.5V, I _D =-20A	-	2.8	4	mΩ
		Vgs=-1.8V, Ip=-20A	-	3.8	8	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-20A	100	-	-	S
Dynamic Characteristics (Note 4)	'					
Input Capacitance	Clss		-	4950	-	PF
Output Capacitance	Coss	V _{DS} =-10V,V _{GS} =0V, F=1.0MHz	-	380	-	PF
Reverse Transfer Capacitance	Crss		-	290	-	PF
Switching Characteristics (Note 4)	'					
Turn-on Delay Time	t _{d(on)}		-	20	_	nS
Turn-on Rise Time	tr	Vdd=-10V,Rgen=3Ω	-	50	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =-4.5V,R _L =0.5Ω	-	100	-	nS
Turn-Off Fall Time	tr	-	-	40	-	nS
Total Gate Charge	Qg		_	100	-	nC
Gate-Source Charge	Qgs	V _{DS} =-10V,I _D =-20A, V _{GS} =-4.5V	-	21	_	nC
Gate-Drain Charge	Qgd	-	-	32	-	nC
Drain-Source Diode Characteristics					I	
Diode Forward Voltage (Note 3)	Vsp	V _{GS} =0V,I _S =-20A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-70	А
Reverse Recovery Time	trr	T _J =25°C, I _F =-10A	-	48	-	nS
Reverse Recovery Charge	Qrr	di/dt=100A/µs (Note 3)	-	55	_	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is n	egligible(tu	ırn-on is d	ominated b	y LS+L

Notes:

- ${\color{blue}\textbf{\textcircled{1}}} \ \, \text{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- ② Surface Mounted on FR4 Board, t≤10sec.
- 3 Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%.
- 4 Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics



-Vds Drain-Source Voltage (V)
Figure 1 Output Characteristics

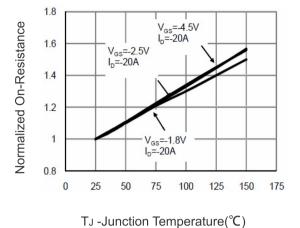


Figure 4 Rdson-Junction Temperature

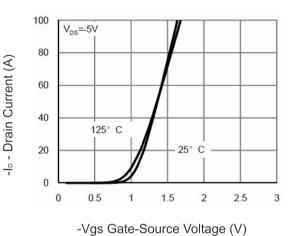


Figure 2 Transfer Characteristics

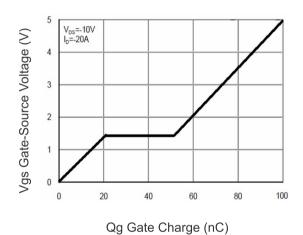


Figure 5 Gate Charge

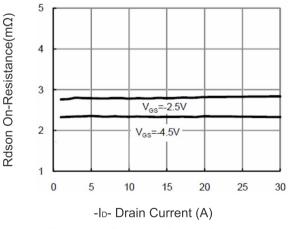


Figure 3 Rdson- Drain Current

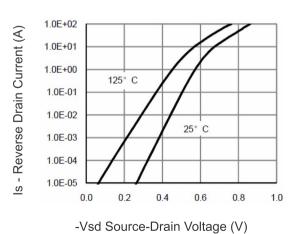


Figure 6 Drain-Source On-Resistance



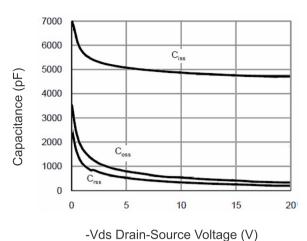
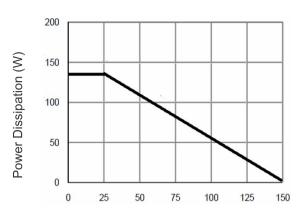


Figure 7 Capacitance vs Vds



T_J -Junction Temperature(°C) Figure 9 Power De-rating

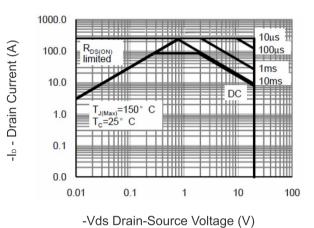
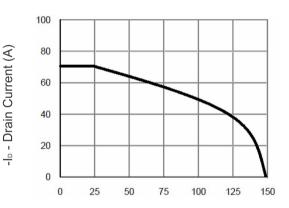
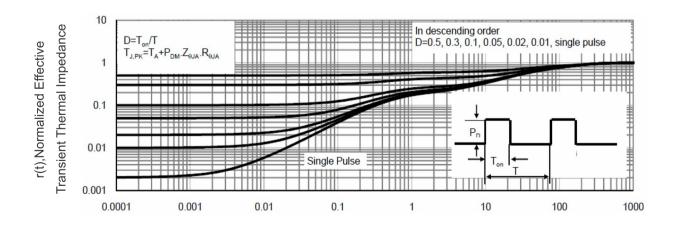


Figure 8 Safe Operation Area



T_J -Junction Temperature(°C) Figure 10 -Current De-rating

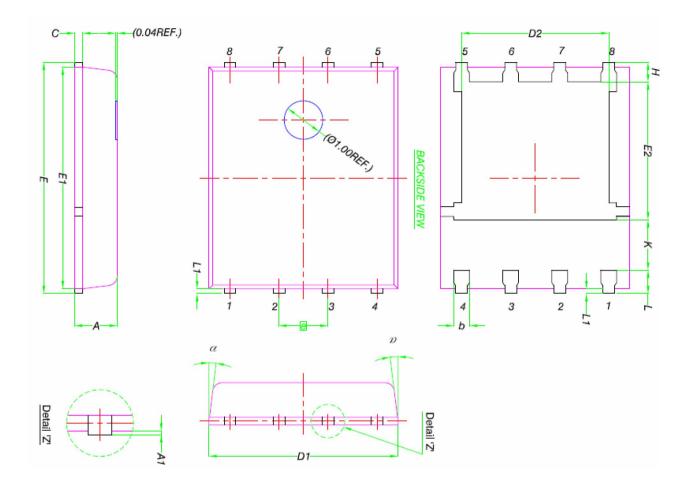


Square Wave Pluse Duration(sec) Figure 11 Normalized Maximum Transient Thermal Impedance

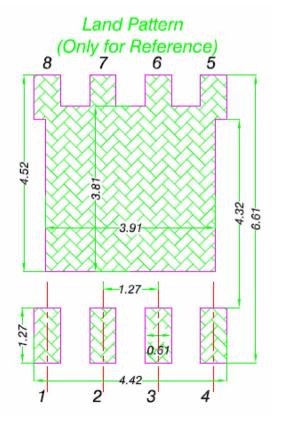




DFN5X6-8L Package Information



5.44	MILLIMETERS			
DIM.	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
A1	0	-	0.05	
b	0.33	0.41	0.51	
С	0.20	0.25	0.30	
D1	4.80	4.90	5.00	
D2	3.61	3.81	3.96	
Ε	5.90	6.00	6.10	
E1	5.70	5.75	5.80	
E2	3.38	3.58	3.78	
е	1.27 BSC			
Н	0.41	0.51	0.61	
K	1.10	-	-	
L	0.51	0.61	0.71	
L1	0.06	0.13	0.20	
α	0°	-	12°	







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